

Material Content Data Sheet

RoHS | Halogen-Free

Sales Product Name	TLE6711GL	**Issued**	18. August 2021
MA#	MA003549484		
Package	PG-DSO-20-66	**Weight***	486.95 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	6.251	1.28	1.28	12837	12837
leadframe	inorganic material	phosphorus	7723-14-0	0.039	0.01		80	
	non noble metal	zinc	7440-66-6	0.155	0.03		319	
	non noble metal	iron	7439-89-6	3.104	0.64		6375	
	non noble metal	copper	7440-50-8	126.041	25.88	26.56	258841	265615
wire	non noble metal	copper	7440-50-8	0.248	0.05	0.05	509	509
encapsulation	organic material	carbon black	1333-86-4	0.689	0.14		1414	
	plastics	epoxy resin	-	31.677	6.51		65052	
	inorganic material	silicondioxide	60676-86-0	311.948	64.08	70.73	640623	707089
leadfinish	non noble metal	tin	7440-31-5	2.746	0.56	0.56	5639	5639
plating	noble metal	silver	7440-22-4	1.621	0.33	0.33	3330	3330
glue	plastics	epoxy resin	-	0.606	0.12		1245	
	noble metal	silver	7440-22-4	1.819	0.37	0.49	3736	4981
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
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This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption.

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